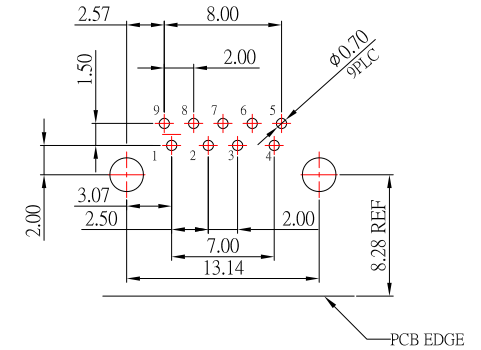
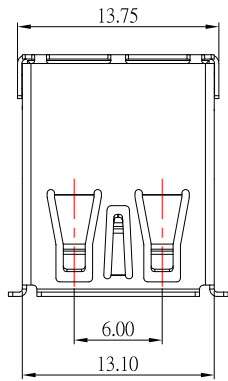




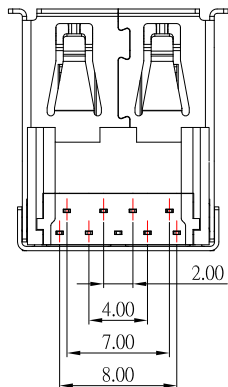
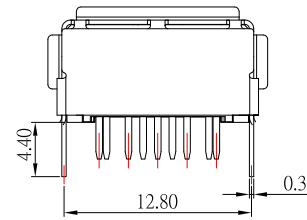
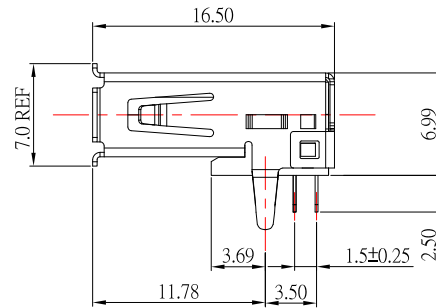
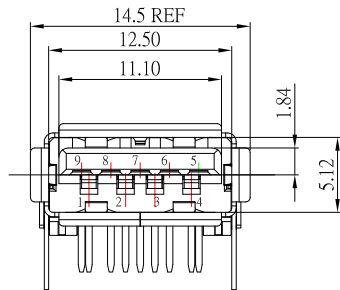
SUA-110H2-30x-S277

鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"



PCB LAYOUT



NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: Brass

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 1.8 Amperes for pin 1 & pin4
0.25 Amperes other contacts
- 3.2 insulator Resistance: 100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max for pin 1 & pin4
50mΩ Max for other contacts
- 3.5 Operation Temperature: -55°C ~ +85°C
- 3.6 Insertion Force: 35 N
- 3.7 Extraction Force: 10 N

PIN NO.	PIN 1	PIN 2	PIN 3	PIN 4
SLGNL NAME	V BUS	D-	D+	GND
REMARK	USB 2.0 CONTACT PINS			

PIN NO.	PIN 5	PIN 6	PIN 7	PIN 8	PIN 9
SLGNL NAME	STDA_SSRX-	STDA_SSRX+	GND_DRAIN	STDA_SSTX-	STDA_SSTX+

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY: Jack Lu
DATE: 04/12/24
CHECKED BY: Jacky Chen
DATE: 04/12/24
APPROVED BY: Tony Kao
DATE: 04/12/24

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	USB 3.0 A/F 90度 DIP 直腳
SCALE	1 : 1	DWG NO.	SUA-110H2-30x-S277
SHEET NO.	1 of 1	PART NO.	SUA-110H2-30x-S277
		SIZE	A4
		VER	R1

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	更新圖面	Jack	041224